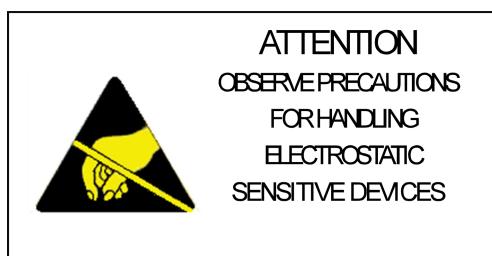


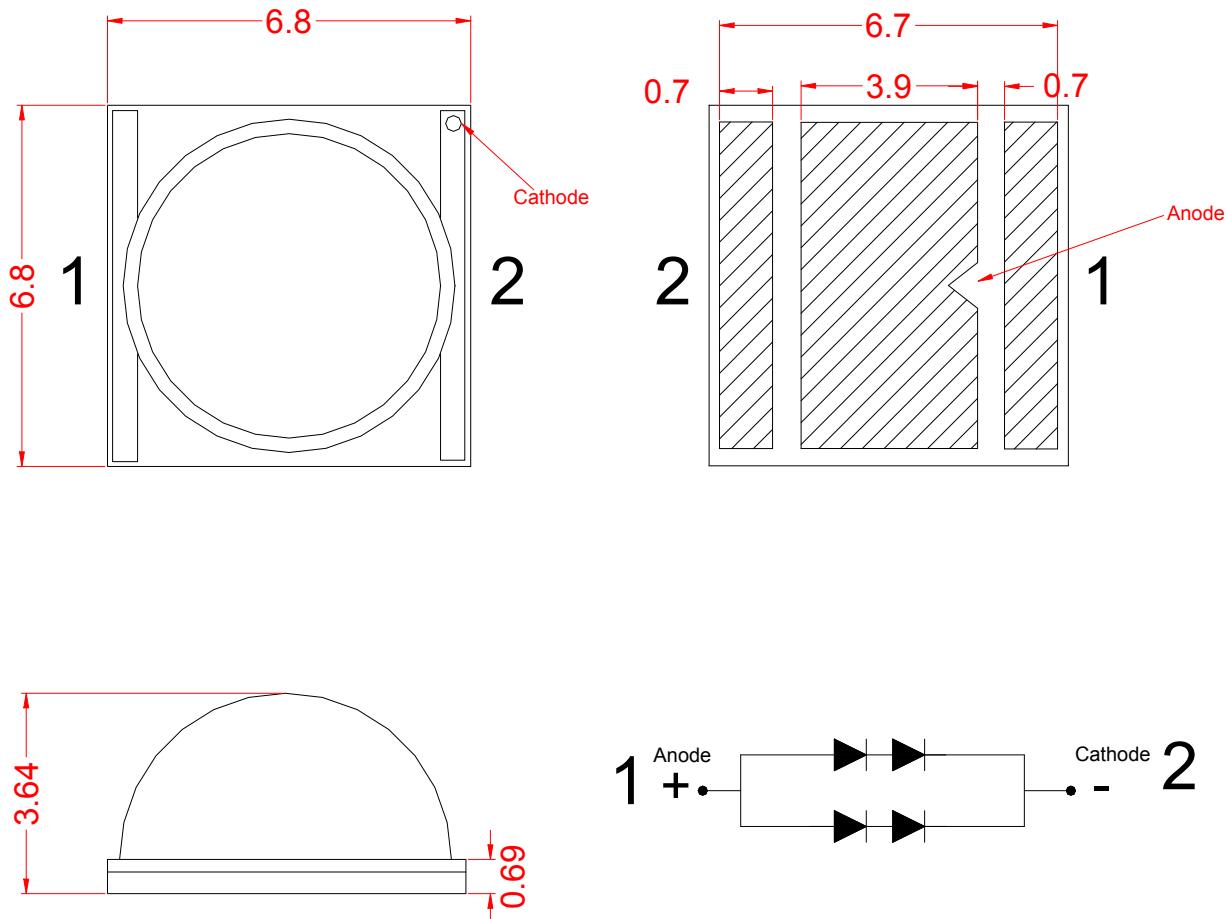
WCN-6868HO-120-4E-V6**SPECIFICATION**

WCN			CUSTOMER Confirmed
Prepared by	Checked by	Approved by	
LiuGuo 2018-11-9	ZhangChun 2018-11-9		



Description

- ◆ Viewing angle:140 deg
- ◆ The materials of the LED dice is AlGaNp
- ◆ 6.8mm×6.8mm×3.64mm
- ◆ RoHS compliant lead-free soldering compatible

Package Outline**NOTES:**

1. All dimensions units are millimeters ;
2. All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted.

Absolute Maximum Ratings at Ta=25°C

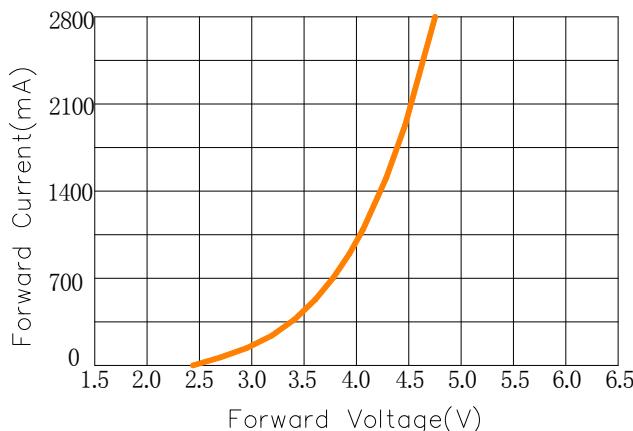
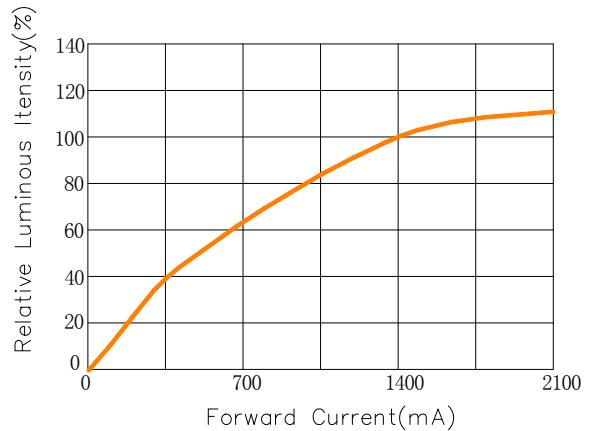
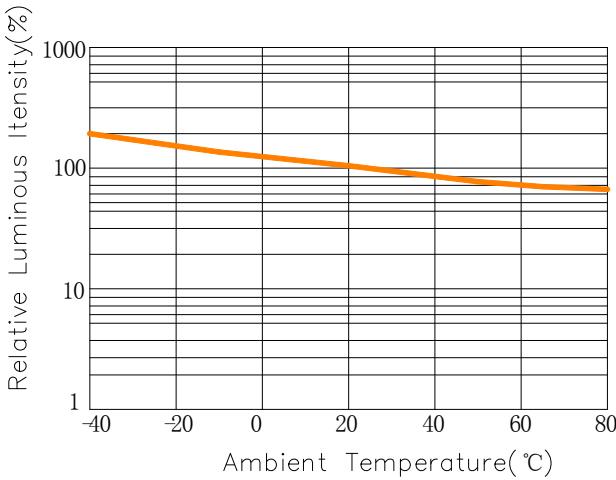
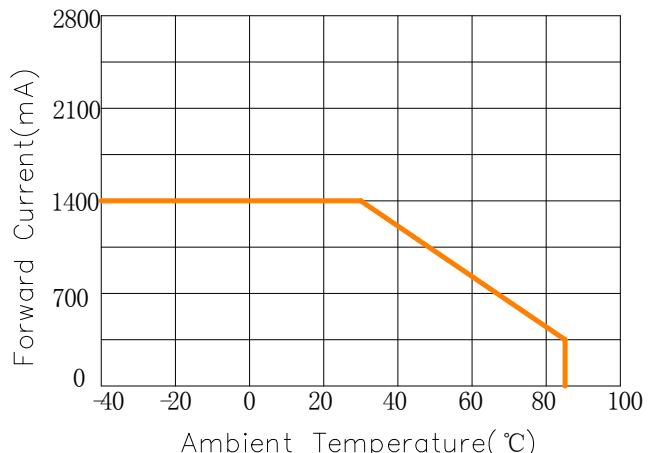
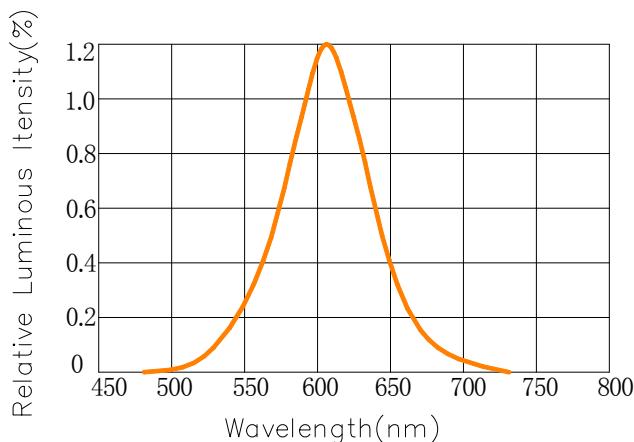
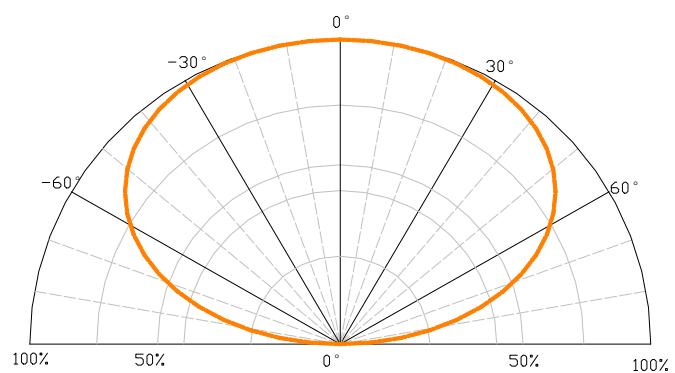
Parameter	Symbol	Rating	Units
Power Dissipation	Pd	6580	mW
Forward current	If	1400	mA
Peak Forward Current	IFP	3000	mA
Reverse voltage	VR	5	V
Electrostatic Discharge	ESD	1000	V
Operating temperature	Topr	-30~+85	°C
Storage temperature	Tstg	-40 ~+100	°C
junction temperature	Tj	95	°C

Electrical/Optical characteristics at Ta=25°C

Item	test condition	Symbol	Value			Unit
			Min.	Typ.	Max.	
Forward voltage	If=1400mA	Vf	3.2	--	3.7	V
			3.7	--	4.2	V
			4.2	--	4.7	V
Luminous intensity	If=1400mA	Iv	400	--	450	LM
			450	--	500	LM
			500	--	550	LM
Dominant wavelength	If=1400mA	λd	600	--	605	nm
			605	--	610	nm
Viewing angle at 50% Iv	If=1400mA	2θ1/2	--	140	--	Deg
Reverse current	Vr=5V	Ir	--	--	10	μA
Thermal resistance	If=1400mA	Rth(j-s)	--	--	450	°C/W

NOTE:

- 1.1/10 Duty cycle, 0.1ms pulse width.
2. The above forward voltage measurement allowance tolerance is 0.1V.
3. the above luminous intensity measurement allowance tolerance ±10%.

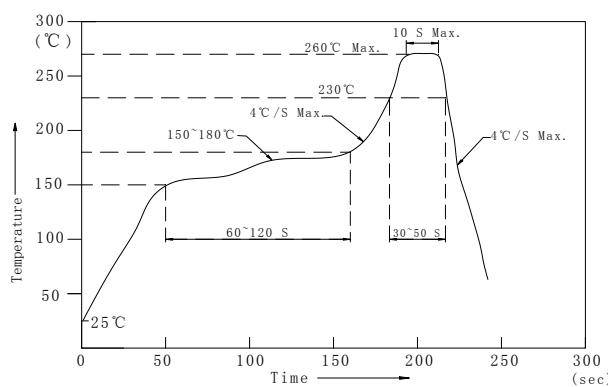
Optical characteristics curves**Forward Current VS Forward Voltage****Relative Flux VS Forward Current****Relative Flux VS Ambient Temperature****Forward Current VS Ambient Temperature****Relative Spectral Distribution****Typical Spectral Distribution**

Test items and results of reliability

Type	Test Item	Test Conditions	Note	Number of Damaged
Environmental Sequence	Reflow	Ta=260°C max T=10s	2 times	0/22
	Temperature Cycle	-40°C 30min ↑↓ 100°C 30min	100 cycle	0/22
	Thermal Shock	-40°C 15min ↑↓ 100°C 15min	100 cycle	0/22
	High Humidity Heat Cycle	30°C ⇄ 65°C 90%RH 24hrs/1cycle	10 cycle	0/22
	High Temperature Storage	Ta=100°C	1000 hrs	0/22
	Low Temperature Storage	Ta=-40°C	1000 hrs	0/22
	Humidity Heat Storage	Ta=60°C RH=90%	1000 hrs	0/22
	Low Temperature Storage	Ta=-30°C	1000 hrs	0/22
Operation Sequence	Life Test	Ta=25°C IF=20mA	1000 hrs	0/22
	High Humidity Heat Life Test	60°C RH=90% IF=10mA	500 hrs	0/22
	Low Temperature Life Test	Ta=-20°C IF=20mA	1000 hrs	0/22

Reflow Profile

■ Reflow Temp/Time



Notes:

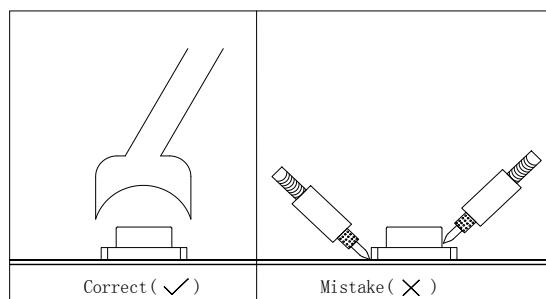
1. We recommend the reflow temperature $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$. the maximum soldering temperature should be limited to 260°C .
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

■ Soldering iron

Basic spec is $\leq 5\text{ sec}$ when 260°C . If temperature is higher, time should be shorter ($+10^{\circ}\text{C} \rightarrow -1\text{ sec}$). Power dissipation of iron should be smaller than 20W , and temperatures should be controllable .Surface temperature of the device should be under 230°C .

■ Rework

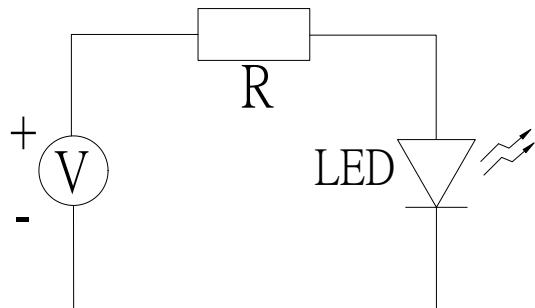
1. Customer must finish rework within 5 sec under 260°C .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



- Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow solder etc.

Test circuit and handling precautions

■ Test circuit



■ Handling precautions

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature : 5°C~30°C(41°F~86°F)

2.2 Shelf life in sealed bag: 12 month at <5°C~30°C and <30% R.H. After the package is

Opened, the products should be used within a week or they should be keeping to stored at ≤ 20 R.H. with zip-lock sealed.

3. Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs. The Conditions are as

followings:

3.1 $70\pm3^\circ\text{C}$ x(12~24hrs) and <5%RH, taped reel type

3.2 $100\pm3^\circ\text{C}$ x(45min~1hr), bulk type

3.3 $130\pm3^\circ\text{C}$ x(15~30min), bulk type